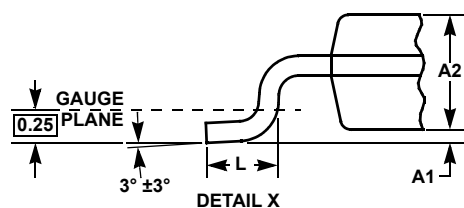
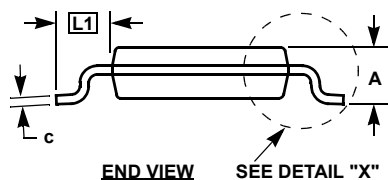
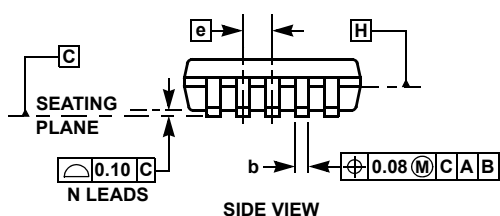
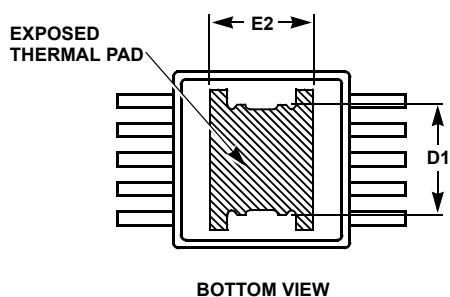
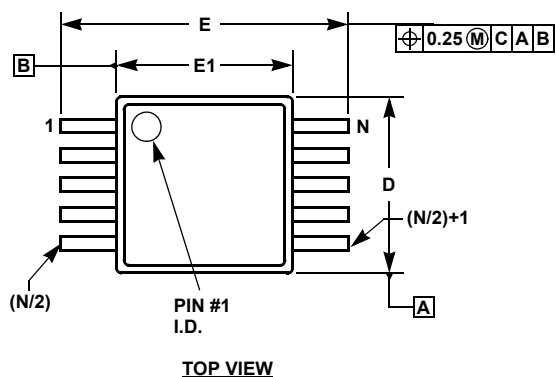


# Plastic Packages for Integrated Circuits

## HMSOP (Heat-Sink MSOP) Package Family



### MDP0050

#### HMSOP (HEAT-SINK MSOP) PACKAGE FAMILY

SYMBOL	MILLIMETERS		TOLERANCE	NOTES
	HMSOP8	HMSOP10		
A	1.00	1.00	Max.	-
A1	0.075	0.075	+0.025/-0.050	-
A2	0.86	0.86	±0.09	-
b	0.30	0.20	+0.07/-0.08	-
c	0.15	0.15	±0.05	-
D	3.00	3.00	±0.10	1, 3
D1	1.85	1.85	Reference	-
E	4.90	4.90	±0.15	-
E1	3.00	3.00	±0.10	2, 3
E2	1.73	1.73	Reference	-
e	0.65	0.50	Basic	-
L	0.55	0.55	±0.15	-
L1	0.95	0.95	Basic	-
N	8	10	Reference	-

Rev. 1 2/07

#### NOTES:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25mm maximum per side are not included.
3. Dimensions "D" and "E1" are measured at Datum Plane "H".
4. Dimensioning and tolerancing per ASME Y14.5M-1994.